

# CM1420, CM1422

## LCD EMI Filter Array with ESD Protection

### Description

The CM1420 and CM1422 are EMI filter arrays with ESD protection, which integrate six and eight Pi-filters (C-R-C), respectively. The CM1420/22 has component values of 15 pF – 100 Ω – 15 pF. These devices include ESD protection diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of ±15 kV, well beyond the maximum requirement of the IEC 61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30 kV.

This device is particularly well suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of its small package format and easy-to-use pin assignments. In particular, the CM1420/22 is ideal for EMI filtering and protecting data lines from ESD for the LCD display in clamshell handsets.

The CM1420 and CM1422 incorporate *OptiGuard™* coating which results in improved reliability at assembly. The CM1420 and CM1422 are available in space-saving, low-profile chip scale packages with RoHS compliant lead-free finishing.

### Features

- Functionally and Pin Compatible with CSPEMI606 (CM1420) and CSPEMI608 (CM1422) Devices
- *OptiGuard™* Coated for Improved Reliability at Assembly
- Six and Eight Channels of EMI Filtering
- ±15 kV ESD Protection on Each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- ±30 kV ESD Protection on Each Channel (HBM)
- Better than 30 dB of Attenuation at 1 GHz to 3 GHz
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum Filter and ESD Performance
- 15-Bump, 2.960 mm x 1.330 mm Footprint Chip Scale Package (CM1420)
- 20-Bump, 4.000 mm x 1.458 mm Footprint Chip Scale Package (CM1422)
- These Devices are Pb-Free and are RoHS Compliant

### Applications

- LCD Data Lines in Clamshell Wireless Handsets
- EMI Filtering & ESD Protection for High-Speed I/O Data Ports
- Wireless Handsets / Cell Phones
- Notebook Computers
- PDAs / Handheld PCs
- EMI Filtering for High-Speed Data Lines



ON Semiconductor®

<http://onsemi.com>

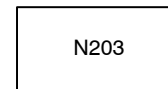


WLCSP15  
CP SUFFIX  
CASE 567BS



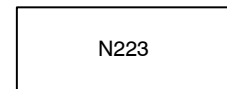
WLCSP20  
CP SUFFIX  
CASE 567BZ

### MARKING DIAGRAM



CM1420

15-Bump CSP Package



CM1422

20-Bump CSP Package

N203 = CM1420-03CP

N223 = CM1422-03CP

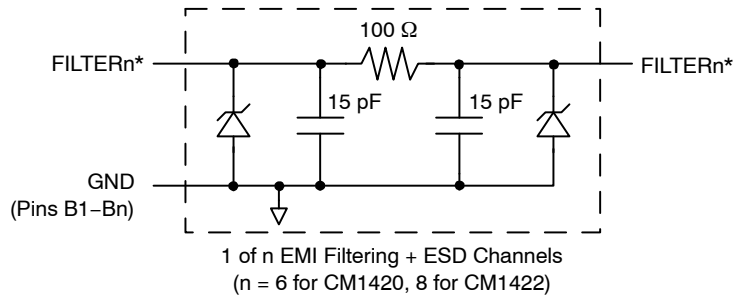
### ORDERING INFORMATION

Device	Package	Shipping†
CM1420-03CP	CSP-15 (Pb-Free)	3500/Tape & Reel
CM1422-03CP	CSP-20 (Pb-Free)	3500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

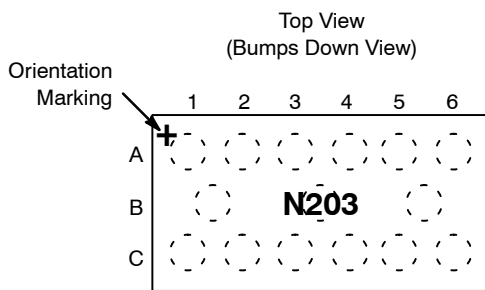
# CM1420, CM1422

## BLOCK DIAGRAM

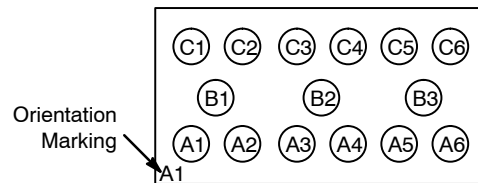


\*See Package/Pinout Diagrams for expanded pin information.

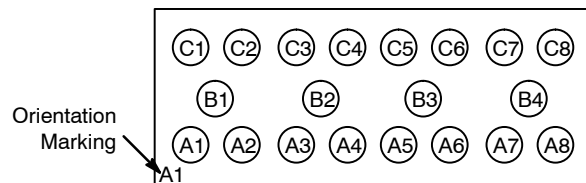
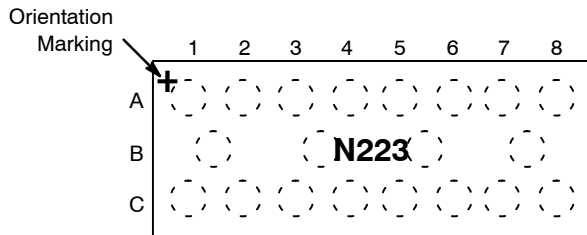
## PACKAGE / PINOUT DIAGRAMS



Bottom View  
(Bumps Up View)



CM1420 CSP Package



CM1422 CSP Package

Table 1. PIN DESCRIPTIONS

CM1420	CM1422	Name	Description	CM1420	CM1422	Name	Description
Pin(s)	Pin(s)			Pin(s)	Pin(s)		
A1	A1	FILTER1	Filter Channel 1	C1	C1	FILTER1	Filter Channel 1
A2	A2	FILTER2	Filter Channel 2	C2	C2	FILTER2	Filter Channel 2
A3	A3	FILTER3	Filter Channel 3	C3	C3	FILTER3	Filter Channel 3
A4	A4	FILTER4	Filter Channel 4	C4	C4	FILTER4	Filter Channel 4
A5	A5	FILTER5	Filter Channel 5	C5	C5	FILTER5	Filter Channel 5
A6	A6	FILTER6	Filter Channel 6	C6	C6	FILTER6	Filter Channel 6
-	A7	FILTER7	Filter Channel 7	-	C7	FILTER7	Filter Channel 7
-	A8	FILTER8	Filter Channel 8	-	C8	FILTER8	Filter Channel 8
B1-B3	B1-B4	GND	Device Ground				

# CM1420, CM1422

## SPECIFICATIONS

**Table 2. ABSOLUTE MAXIMUM RATINGS**

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	500	mW

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

**Table 3. STANDARD OPERATING CONDITIONS**

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

**Table 4. ELECTRICAL OPERATING CHARACTERISTICS** (Note 1)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
R	Resistance		80	100	120	Ω
C	Capacitance	At 2.5 V DC, 1 MHz, 30 mV AC	12	15	18	pF
V <sub>DIODE</sub>	Diode Standoff Voltage	I <sub>DIODE</sub> = 10 μA		6.0		V
I <sub>LEAK</sub>	Diode Leakage Current (reverse bias)	V <sub>DIODE</sub> = 3.3 V		100	200	nA
V <sub>SIG</sub>	Signal Clamp Voltage Positive Clamp Negative Clamp	I <sub>LOAD</sub> = 10 mA (Note 3)	5.6 -1.5	6.8 -0.8	9.0 -0.4	V
V <sub>ESD</sub>	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	(Note 2)	±30 ±15			kV
R <sub>DYN</sub>	Dynamic Resistance Positive Negative			2.30 0.90		Ω
f <sub>C</sub>	Cut-off Frequency Z <sub>SOURCE</sub> = 50 Ω, Z <sub>LOAD</sub> = 50 Ω	R = 100 Ω, C = 15 pF		120		MHz

1. T<sub>A</sub> = 25 °C unless otherwise specified.
2. ESD applied to input and output pins with respect to GND, one at a time.
3. Clamping voltage is measured at the opposite side of the EMI filter to the ESD pin. For example, if ESD is applied to Pin A1, then clamping voltage is measured at Pin C1.

# CM1420, CM1422

## PERFORMANCE INFORMATION

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

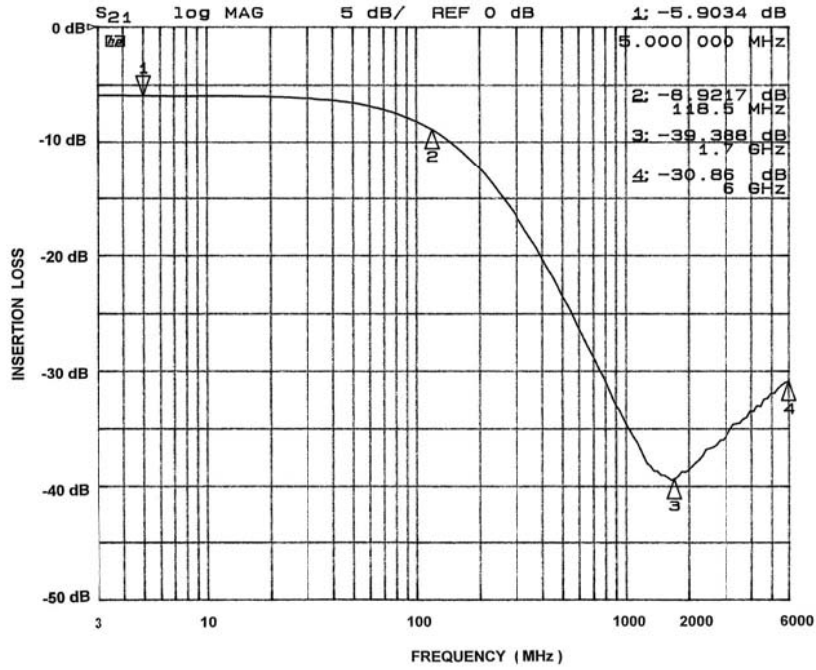


Figure 1. Insertion Loss vs. Frequency (A1-C1 to GND B1)

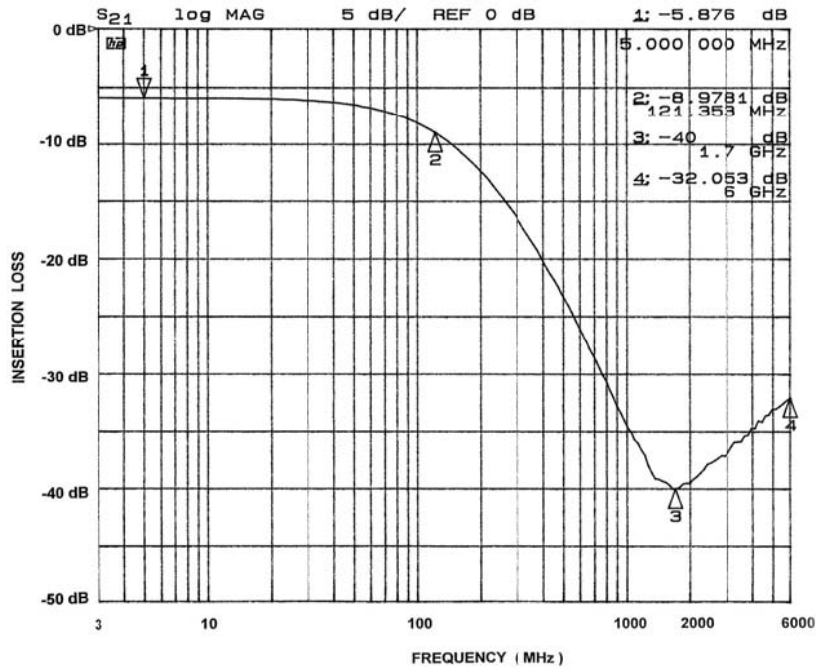


Figure 2. Insertion Loss vs. Frequency (A2-C2 to GND B1)

# CM1420, CM1422

## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

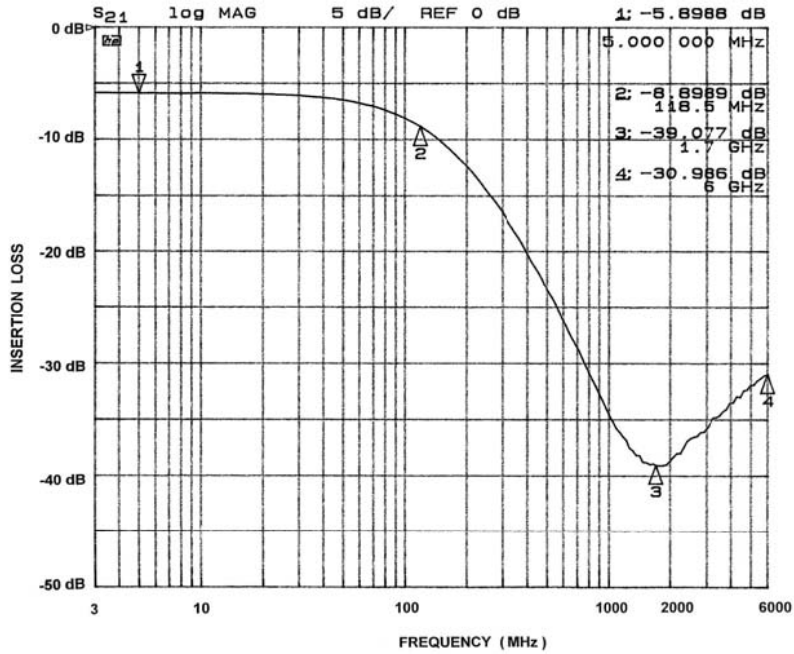


Figure 3. Insertion Loss vs. Frequency (A3-C3 to GND B2)

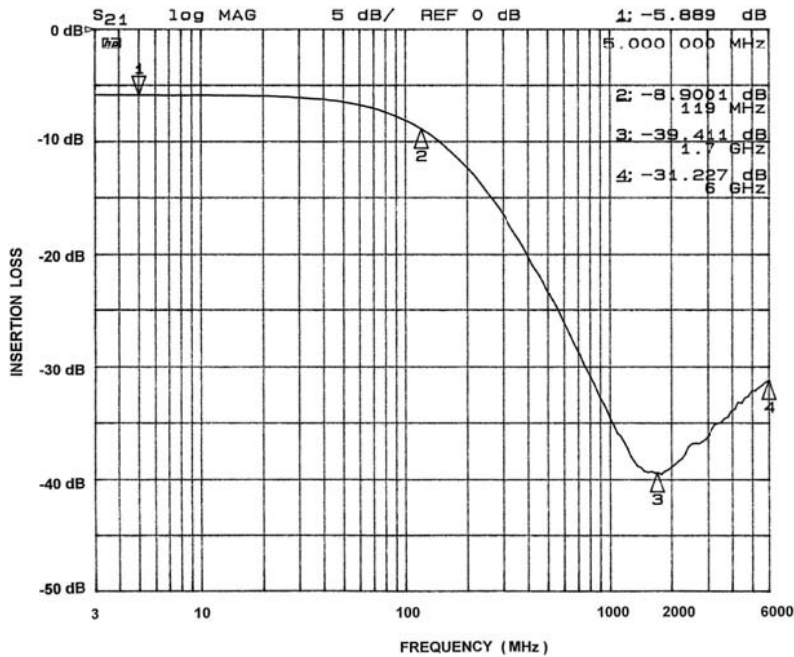


Figure 4. Insertion Loss vs. Frequency (A4-C4 to GND B2)

# CM1420, CM1422

## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

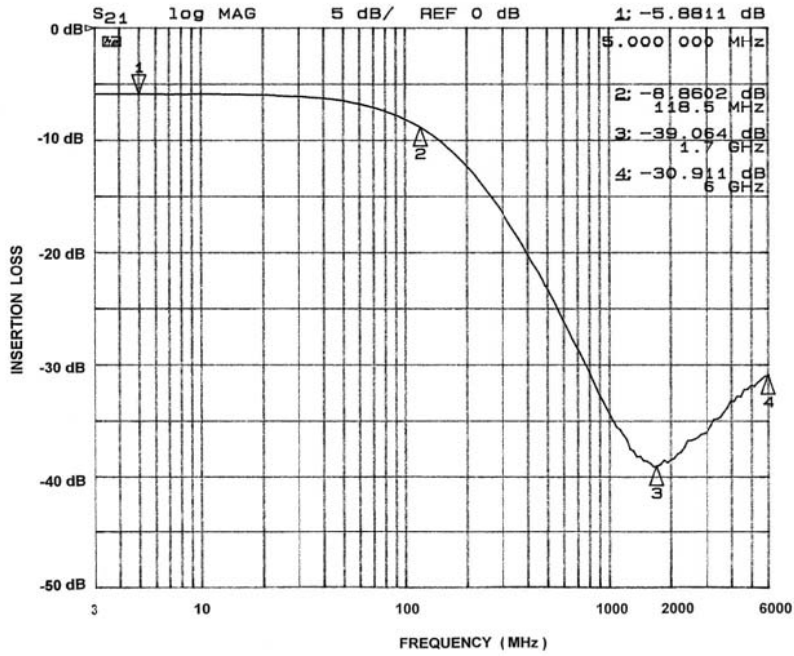


Figure 5. Insertion Loss vs. Frequency (A5-C5 to GND B3)

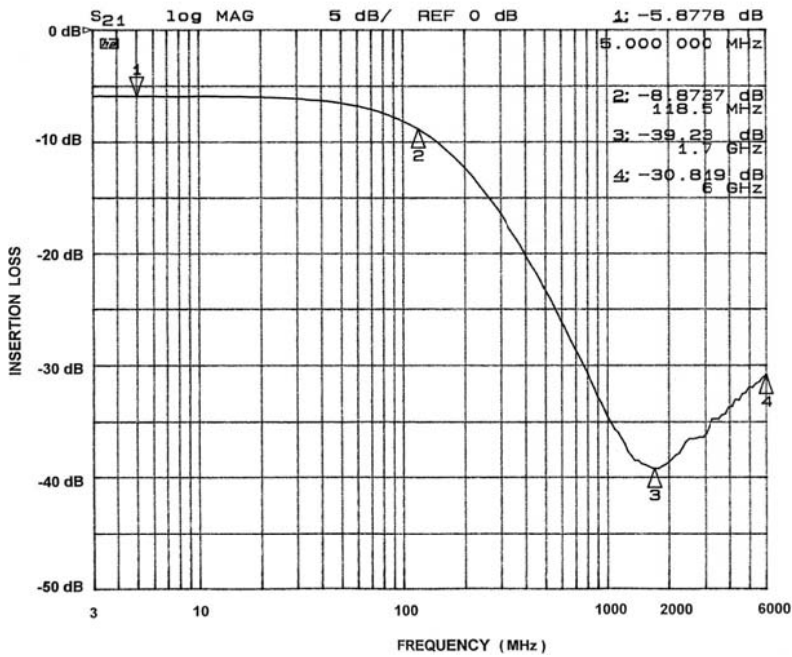


Figure 6. Insertion Loss vs. Frequency (A6-C6 to GND B3)

# CM1420, CM1422

## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

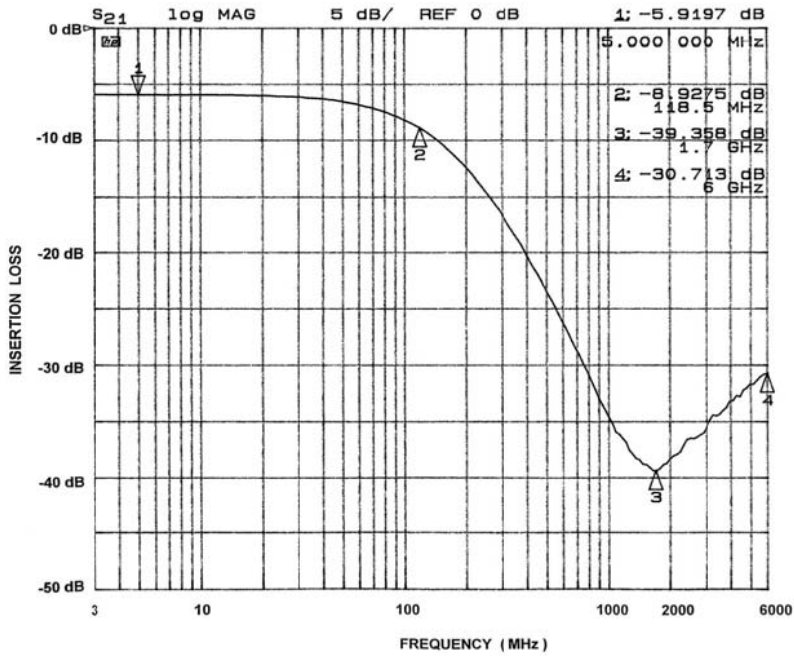


Figure 7. Insertion Loss vs. Frequency  
(A7-C7 to GND B4, CM1422 Only)

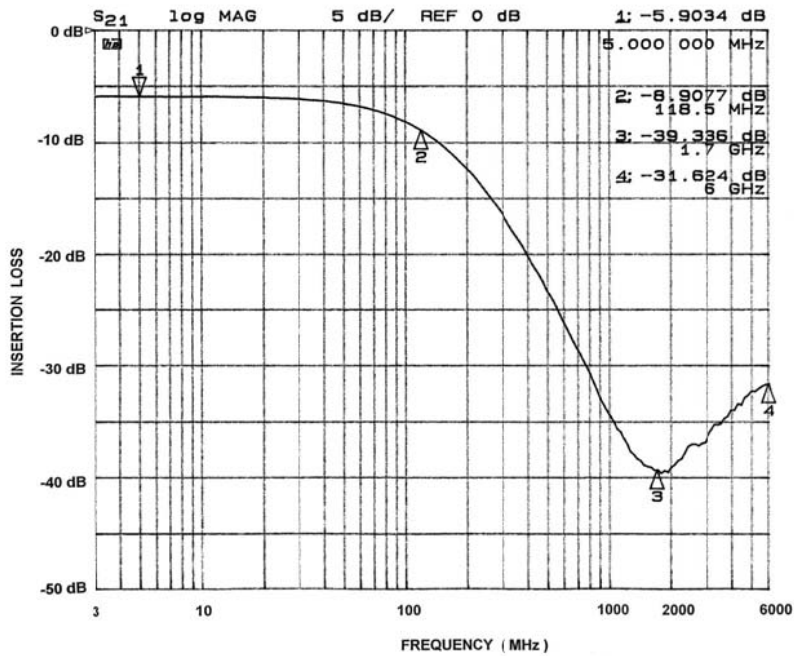
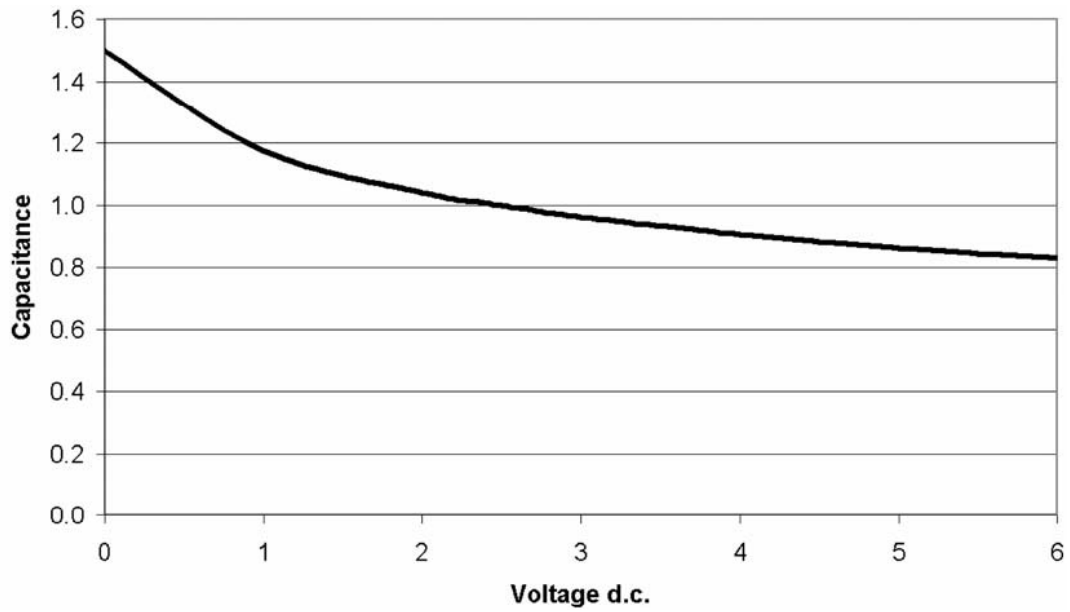


Figure 8. Insertion Loss vs. Frequency  
(A8-C8 to GND B4, CM1422 Only)

# CM1420, CM1422

## PERFORMANCE INFORMATION (Cont'd)



**Figure 9. Filter Capacitance vs. Input Voltage over Temperature  
(normalized to capacitance at 2.5 VDC and 25°C)**

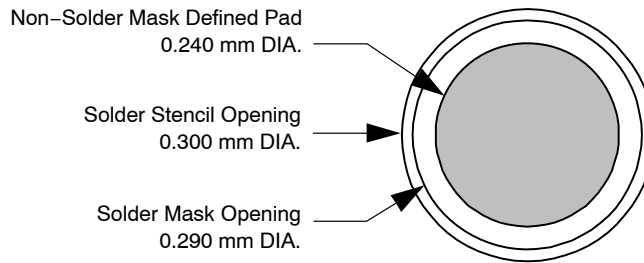


# CM1420, CM1422

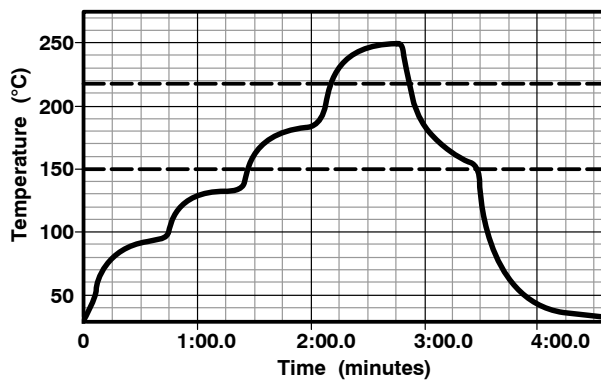
## APPLICATION INFORMATION

**Table 5. PRINTED CIRCUIT BOARD RECOMMENDATIONS**

Parameter	Value
Pad Size on PCB	0.240 mm
Pad Shape	Round
Pad Definition	Non-Solder Mask defined pads
Solder Mask Opening	0.290 mm Round
Solder Stencil Thickness	0.125 – 0.150 mm
Solder Stencil Aperture Opening (laser cut, 5% tapered walls)	0.300 mm Round
Solder Flux Ratio	50/50 by volume
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance – Edge To Corner Ball	±50 µm
Solder Ball Side Coplanarity	±20 µm
Maximum Dwell Time Above Liquidous	60 seconds
Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste	260°C



**Figure 10. Recommended Non-Solder Mask Defined Pad Illustration**

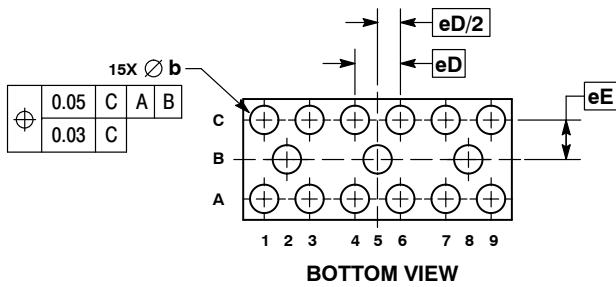
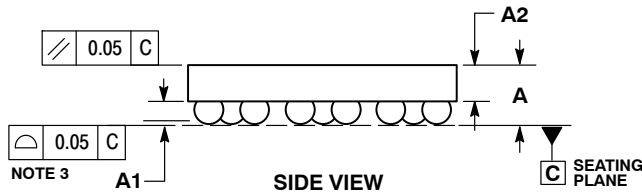
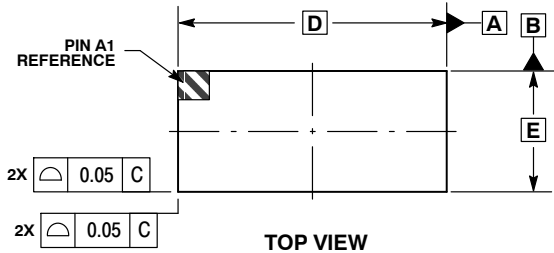


**Figure 11. Lead-free (SnAgCu) Solder Ball Reflow Profile**

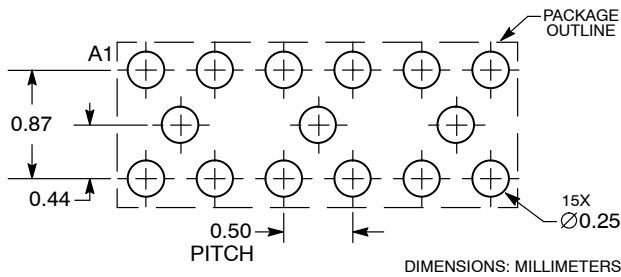
# CM1420, CM1422

## PACKAGE DIMENSIONS

WLCSP15, 2.96x1.33  
CASE 567BS-01  
ISSUE O



### RECOMMENDED SOLDERING FOOTPRINT\*



#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

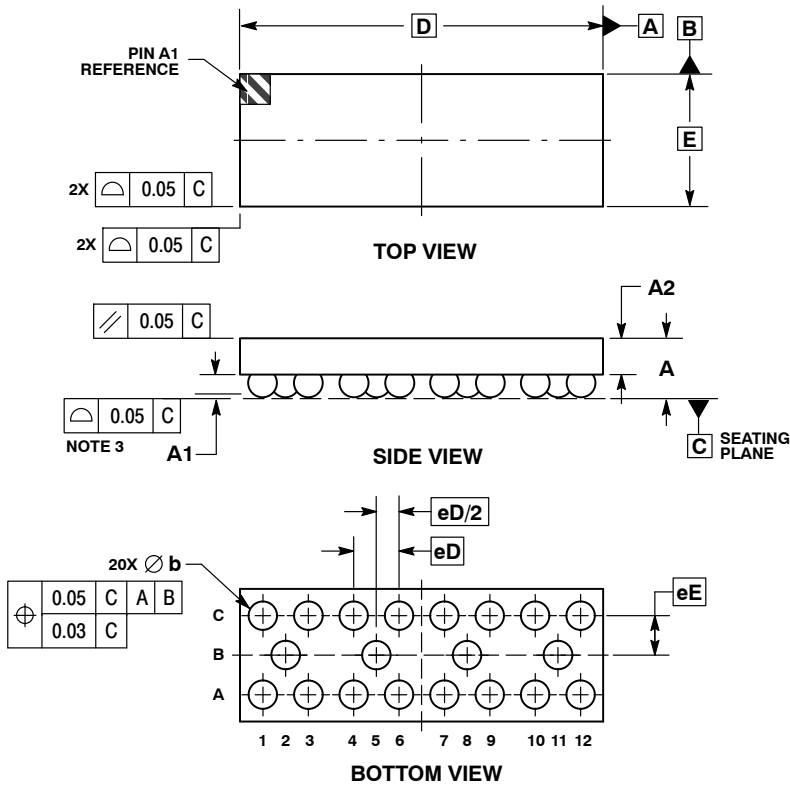
DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40 REF	
b	0.29	0.35
D	2.96 BSC	
E	1.33 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# CM1420, CM1422

## PACKAGE DIMENSIONS

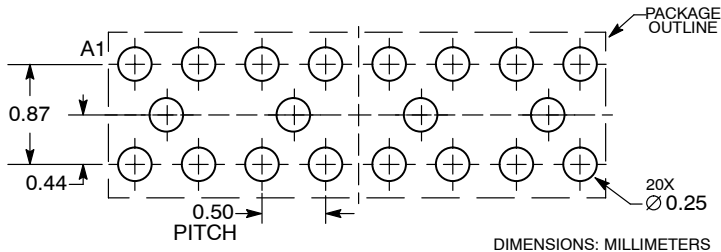
WLCSP20, 4.00x1.46  
CASE 567BZ-01  
ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40 REF	
b	0.29	0.35
D	4.00 BSC	
E	1.46 BSC	
eD	0.50 BSC	
eE	0.435 BSC	

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

OptiGuard™ is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:  
Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free  
USA/Canada  
Europe, Middle East and Africa Technical Support:  
Phone: 421 33 790 2910  
Japan Customer Focus Center  
Phone: 81-3-5773-3850

ON Semiconductor Website: [www.onsemi.com](http://www.onsemi.com)  
Order Literature: <http://www.onsemi.com/orderlit>  
For additional information, please contact your local Sales Representative